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By: 

Date: Apr. 18, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Gottfried Ferber et al.
Applic. No. : 10/056,770
Filed : January 24, 2002
Title : Semiconductor Module and Method for
Fabricating the Semiconductor Module

P R E L I M I N A R Y A M E N D M E N T

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

S i r :

Preliminary to examination, kindly amend the above-identified application as follows:

In the Claims:

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Sub B.1
A1
Claim 1 (amended). A semiconductor module, comprising:

a substrate body having an insulating ceramic layer with a top side, and a metal layer fixedly joined to said top side of said insulating ceramic layer;